

ABSTRACT

One embodiment of the invention relates to a microdevice package containing getters for maintaining a constant vacuum level within the sealed microdevice package. A stacked wafer assembly, containing a plurality of microdevice packages, is formed by aligning a bottom cover wafer with a center wafer. The bottom cover wafer includes one or more bond pads to receive one or more getters. The center wafer includes one or more vias substantially aligned and corresponding to the one or more bond pads. One or more getters are inserted into the one or more vias. The stacked wafer assembly is completed by aligning a top cover wafer opposite the bottom cover wafer to sandwich the center wafer in between. A constant vacuum level is maintained inside the microdevice packages by aligning the wafers, activating the getters, and sealing the microdevice packages in a given sequence.